

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:

Kie Y. Ahn et al.

Examiner:

David S. Blum

Serial No.:

09/945535

Group Art Unit:

2813

Filed:

August 30, 2001

Docket:

1303.026US1

Title:

HIGHLY RELIABLE AMORPHOUS HIGH-K GATE OXIDE ZrO2

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 et. seq., the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicants respectfully request that this Supplemental Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicants request that a copy of the 1449 form, initialed as being considered by the Examiner, be returned to the Applicants with the next official communication.

Pursuant to 37 C.F.R. §1.97(c)(2), Applicants have included the fee of \$180.00 as set forth in 37 C.F.R. §1.17(p). Please charge any additional fees or credit any overpayment to Deposit Account No. 19-0743.

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The Examiner is invited to contact the Applicants' Representative at the below-listed telephone number if there are any questions regarding this communication.

Respectfully submitted,

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By their Representatives,

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Date 10-1-03

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Reg. No. 47,857

<u>CERTIFICATE UNDER 37 CFR 1.8:</u> The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this <u>1st</u> day of October, 2003.

Amy Moriarty

Signatur

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on of information unless it contains a valid OMB control number.

Substitute for form 1449A/PTO Complete if Known INFORMATION DISCLOSURE 09/945535 **Application Number** STATEMENT BY APPLICANT August 30, 2001 Filing Date (Use as`-many sheets as necessary) Ahn, Kie **First Named Inventor** OCT 0 3 2003 **Group Art Unit** 2813 Blum, David **Examiner Name** Attorney Docket No: 1303.026US1

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Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it contains a valid OMB control number. Substitute for form 1449A/PTO Complete if Known INFORMATION DISCLOSURE 09/945535 **Application Number** STATEMENT BY APPLICANE (Use as many sheets as necessary) Filing Date August 30, 2001 Ahn, Kie **First Named Inventor** OCT 0 3 2003 **Group Art Unit** 2813 Blum, David **Examiner Name** Attorney Docket No: 1303.026US1 Sheet 7 of 8

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